



30V N+P Dual Channel MOSFETs

General Description

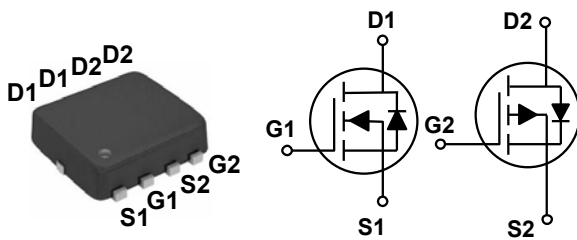
These N+P dual Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV _{DSS}	R _{DS(ON)}	I _D
30 V	20 mΩ	12 A
-30 V	50 mΩ	-8 A

Features

- Fast switching
- Green Device Available
- Suit for 4.5V Gate Drive Applications

PPAK3x3 Dual Pin Configuration



Applications

- DC Fan
- Motor Drive Applications
- Networking
- Half / Full Bridge Topology

Absolute Maximum Ratings T_C=25°C unless otherwise noted

Symbol	Parameter	Rating		Units
V _{DS}	Drain-Source Voltage	30	-30	V
V _{GS}	Gate-Source Voltage	±20	±20	V
I _D	Drain Current - Continuous (T _C =25°C)	12	-8	A
	Drain Current - Continuous (T _C =100°C)	7.2	-4.8	A
I _{DM}	Drain Current - Pulsed (NOTE 1)	48	-32	A
EAS	Single Pulse Avalanche Energy (NOTE 2 · 6)	14	5	mJ
IAS	Single Pulse Avalanche Current (NOTE 2)	17	-10	A
P _D	Power Dissipation (T _C =25°C)	20		W
T _J	Operating Junction Temperature Range	-55 to 150		°C
T _{STG}	Storage Temperature Range	-55 to 150		°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to Ambient	---	62.5	°C/W
R _{θJC}	Thermal Resistance Junction to Case	---	6.4	°C/W

**30V N+P Dual Channel MOSFETs****N Channel Electrical Characteristics (T_J=25°C, unless otherwise noted)****Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	30	---	---	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =30V, V _{GS} =0V, T _J =25°C	---	---	1	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =10A	---	---	20	mΩ
		V _{GS} =4.5V, I _D =6A	---	---	30	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.2	---	2.5	V
gfs	Forward Transconductance	V _{DS} =5V, I _D =6A	---	13	---	S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q _g	Total Gate Charge	V _{DS} =15V, V _{GS} =4.5V, I _D =8A (NOTE 3、4)	---	4.1	---	nC
Q _{gs}	Gate-Source Charge		---	1	---	
Q _{gd}	Gate-Drain Charge		---	2.1	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =15V, V _{GS} =10V, R _G =6Ω, I _D =1A (NOTE 3、4)	---	2.8	---	nS
T _r	Rise Time		---	7.2	---	
T _{d(off)}	Turn-Off Delay Time		---	15.8	---	
T _f	Fall Time		---	4.6	---	
C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =0V, F=1MHz	---	345	---	pF
C _{oss}	Output Capacitance		---	55	---	
C _{rss}	Reverse Transfer Capacitance		---	32	---	
R _g	Gate Resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz	---	3.2	---	Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V, Force Current	---	---	12	A
I _{SM}	Pulsed Source Current		---	---	24	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =1A, T _J =25°C	---	---	1	V

NOTES :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=17A, R_G=25Ω, Starting T_J=25°C.
3. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
4. Essentially independent of operating temperature.



Characteristics Curves

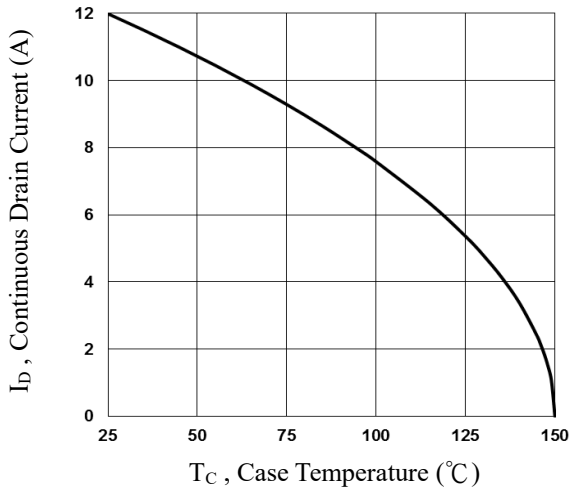


Fig.1 Continuous Drain Current vs. T_c

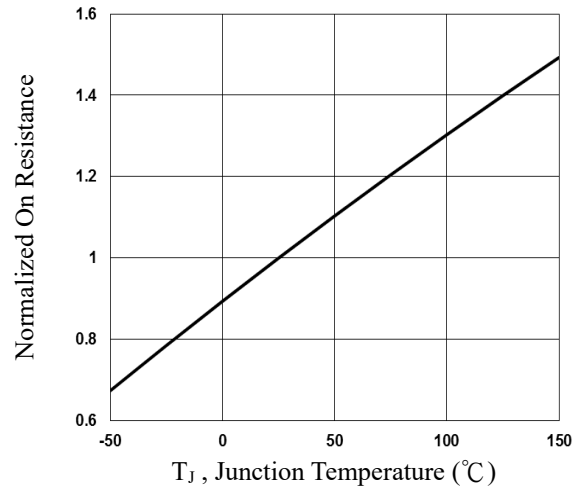


Fig.2 Normalized $R_{DS(on)}$ vs. T_j

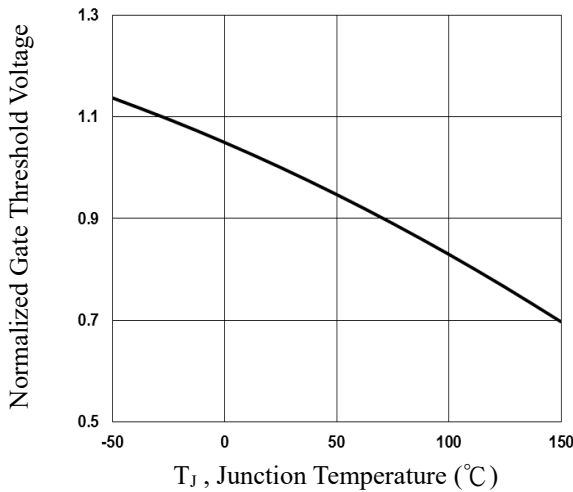


Fig.3 Normalized V_{th} vs. T_j

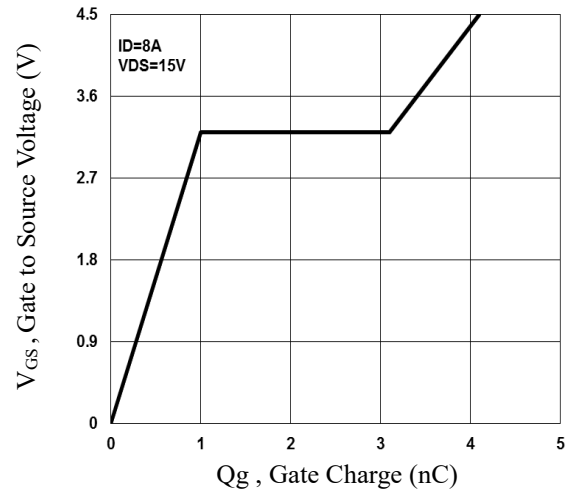


Fig.4 Gate Charge Waveform

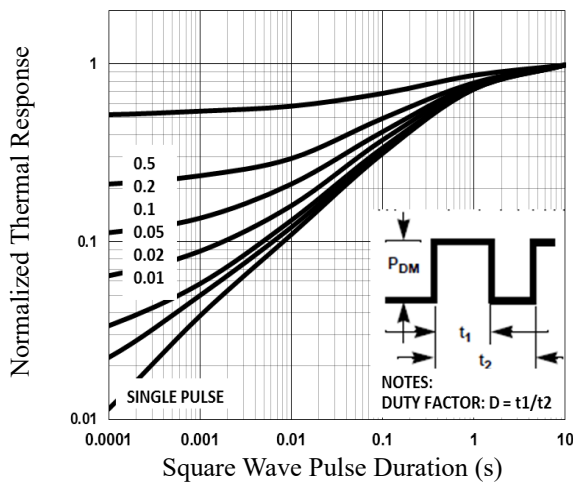


Fig.5 Normalized Transient Response

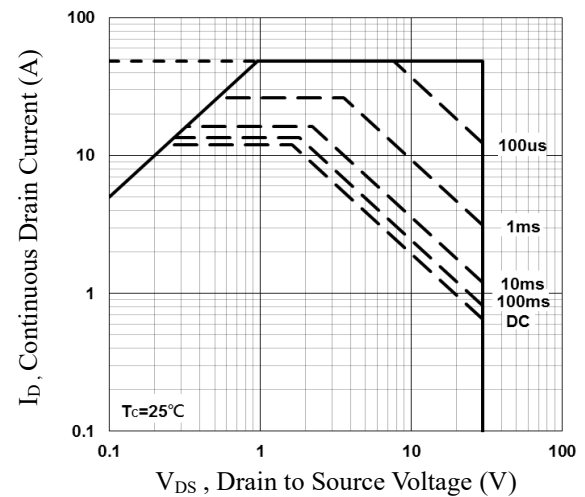


Fig.6 Maximum Safe Operation Area



30V N+P Dual Channel MOSFETs

P Channel Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V , I _D = -250uA	-30	---	---	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} = -30V , V _{GS} = 0V , T _J =25°C	---	---	-1	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} = ±20V , V _{DS} = 0V	---	---	±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} = -10V , I _D = -5A	---	---	50	mΩ
		V _{GS} = -4.5V , I _D = -3A	---	---	75	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D = -250uA	-1.2	---	-2.5	V
gfs	Forward Transconductance	V _{DS} = -10V , I _D = -3A	---	3.5	---	S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q _g	Total Gate Charge	V _{DS} = -15V , V _{GS} = -4.5V , I _D = -3A (NOTE 7 · 8)	---	5.1	---	nC
Q _{gs}	Gate-Source Charge		---	2	---	
Q _{gd}	Gate-Drain Charge		---	2.2	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} = -15V , V _{GS} = -10V , R _G = 6Ω , I _D = -1A (NOTE 7 · 8)	---	3.4	---	nS
T _r	Rise Time		---	10.8	---	
T _{d(off)}	Turn-Off Delay Time		---	26.9	---	
T _f	Fall Time		---	6.9	---	
C _{iss}	Input Capacitance	V _{DS} = -15V , V _{GS} = 0V , F= 1MHz	---	560	---	pF
C _{OSS}	Output Capacitance		---	55	---	
C _{rSS}	Reverse Transfer Capacitance		---	40	---	

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V , Force Current	---	---	-8	A
I _{SM}	Pulsed Source Current		---	---	-16	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V , I _S = -1A , T _J =25°C	---	---	-1	V

NOTES :

5. Repetitive Rating : Pulsed width limited by maximum junction temperature.
6. V_{DD}=-25V, V_{GS}=-10V, L=0.1mH, I_{AS}=-10A, R_G=25Ω, Starting T_J=25°C.
7. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
8. Essentially independent of operating temperature.



Characteristics Curves

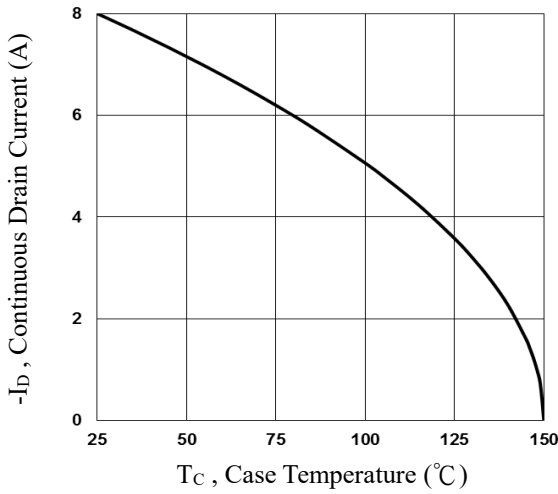


Fig.7 Continuous Drain Current vs. Tc

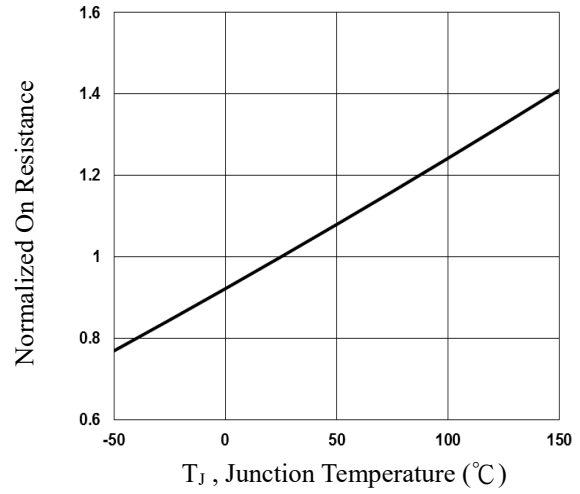


Fig.8 Normalized RDSON vs. Tj

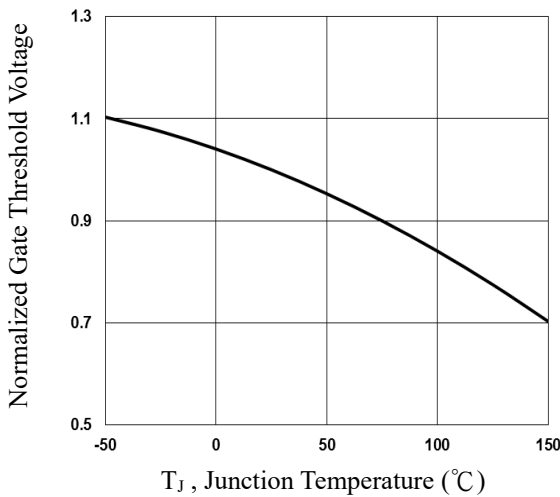


Fig.9 Normalized Vth vs. Tj

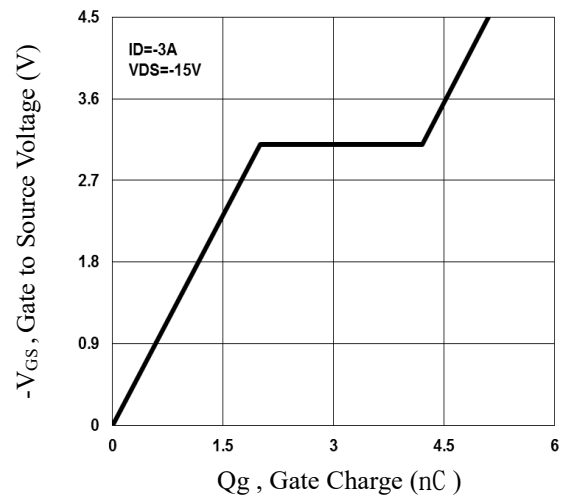


Fig.10 Gate Charge Waveform

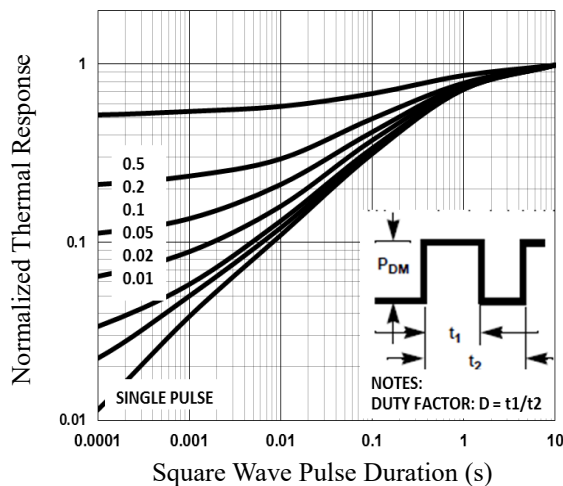


Fig.11 Normalized Transient Impedance

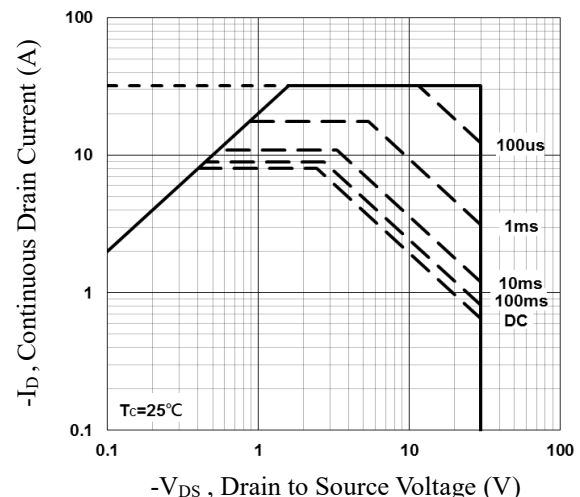


Fig.12 Maximum Safe Operation Area

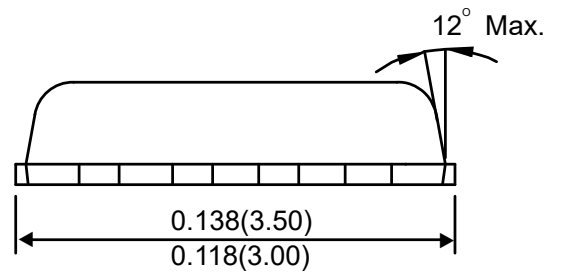
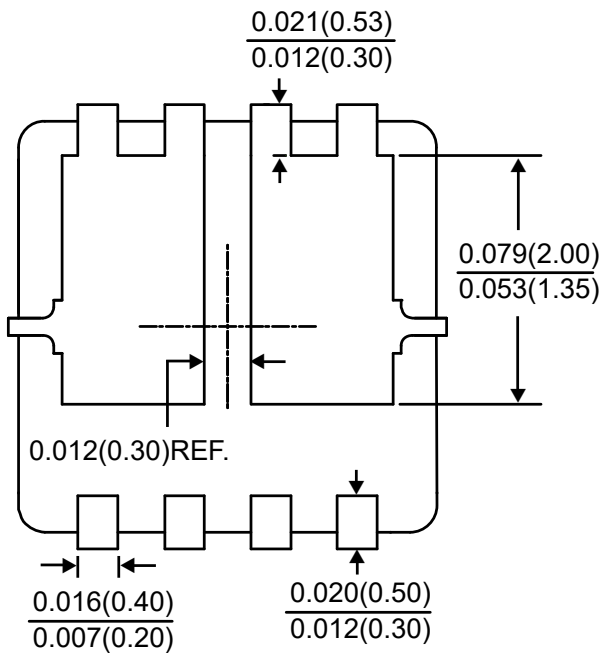
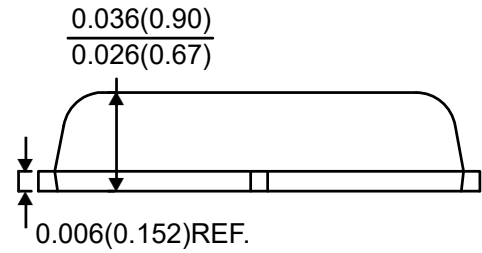
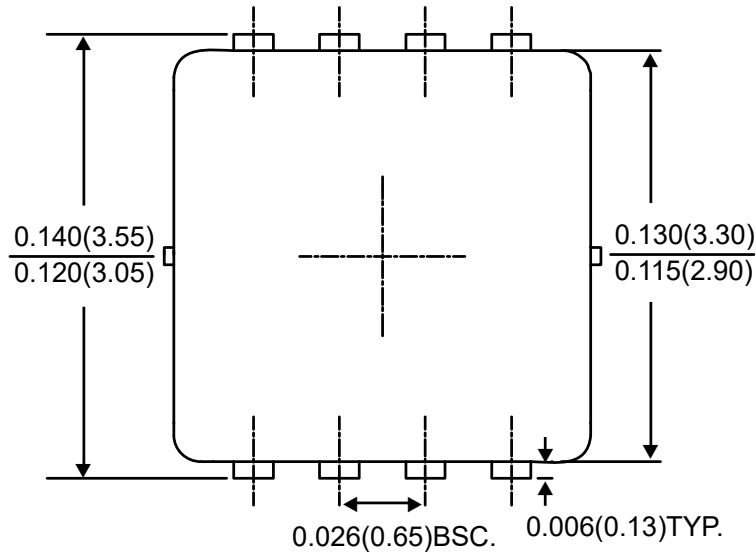


P3MBC020A



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Package Outline Dimensions



PPAK3x3 Dual

Dimensions in inches and (millimeters)



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